

INDUSTRIAL PRU1 ICSSM RGMII/MII ADD ON BOARD
PROC167E1

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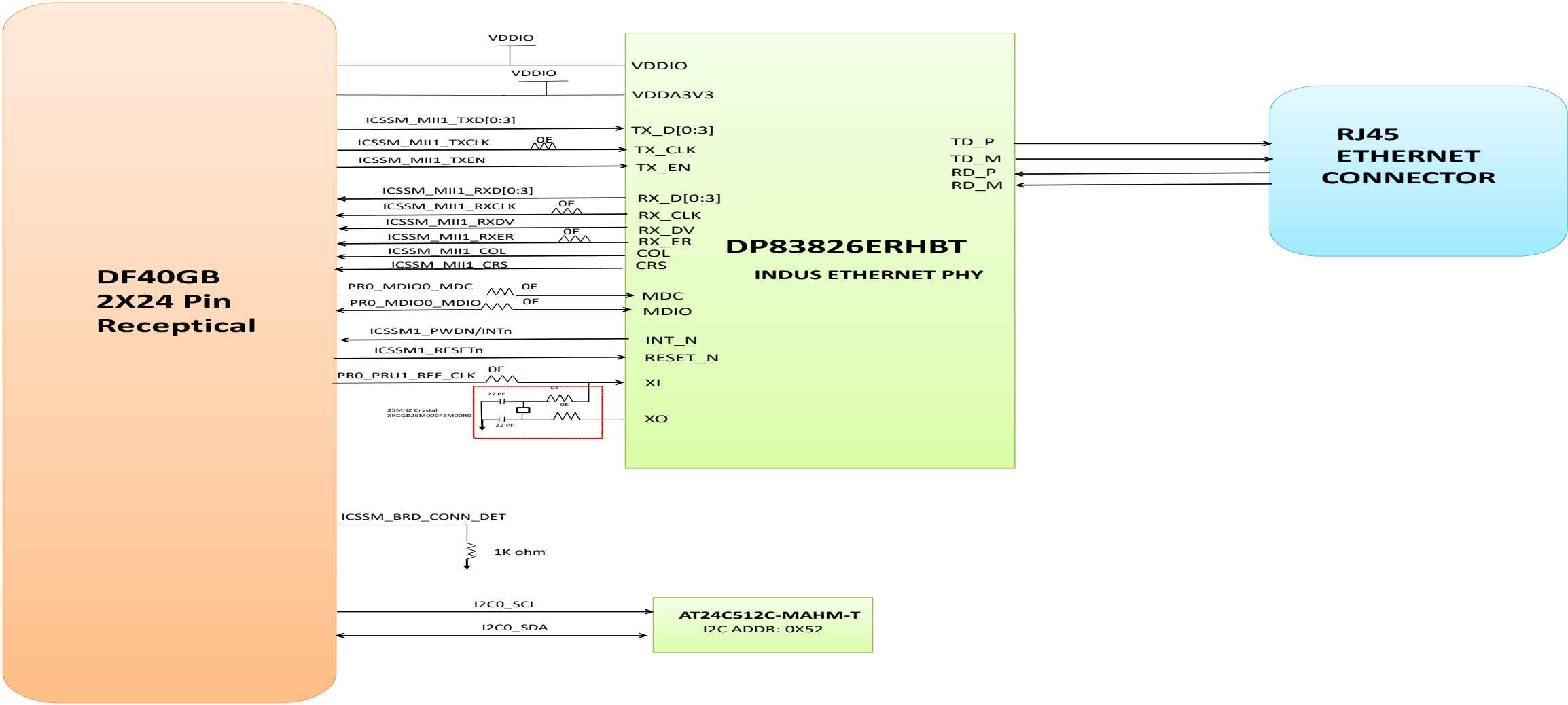
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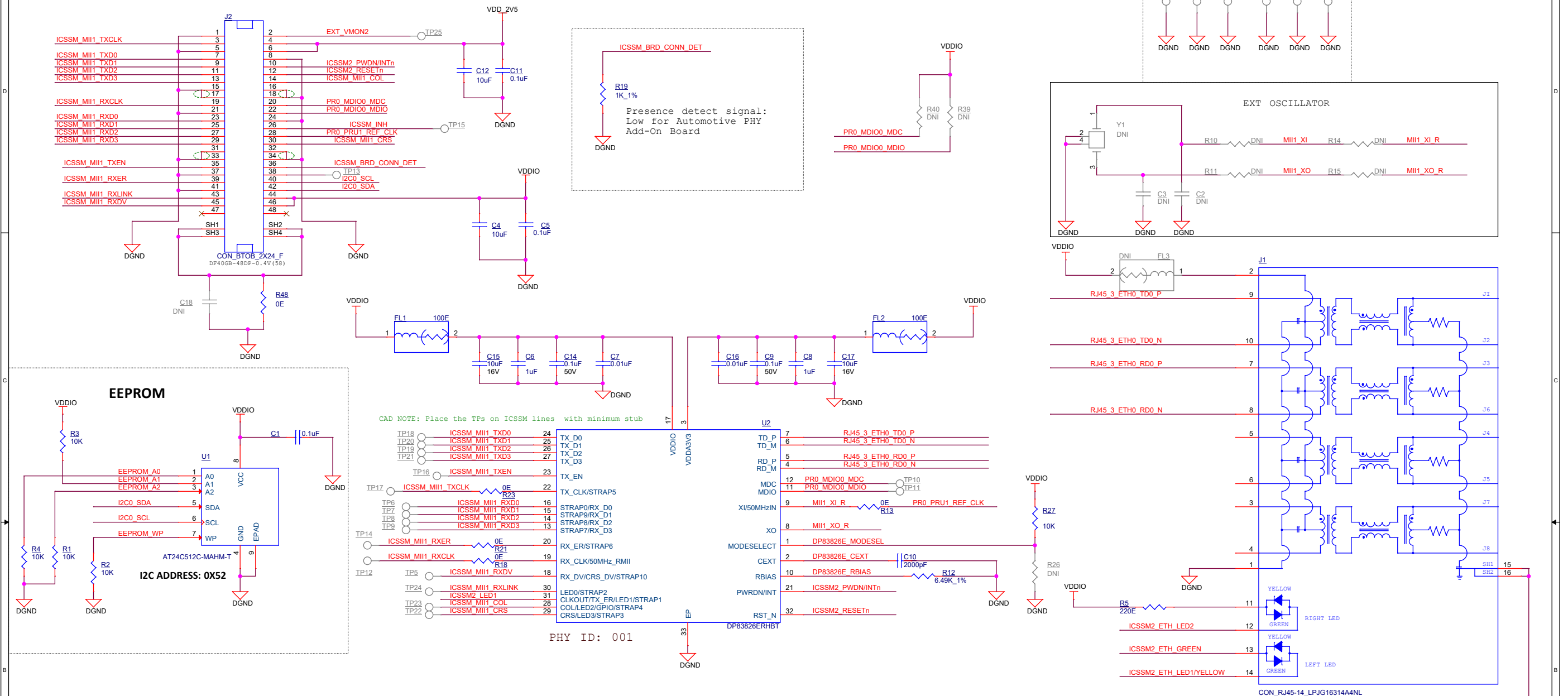
REVISION HISTORY

VER #	DATE	DESCRIPTION OF CHANGES	AUTHOR	REVIEWED BY	APPROVED BY
0.01	18 APRIL 2023	Initial Draft	Mistral Design Team	TI	
0.02	3 MAY 2023	Updated for TI's review comments	Mistral Design Team		
0.03	9 JUNE 2023	Added RC filter across ethernet board connector (J2)	Mistral Design Team		
0.04	16 OCT 2023	Added NOTES, HW & LABELS page to include Fiducial marks and CE mark etc	Mistral Design Team		

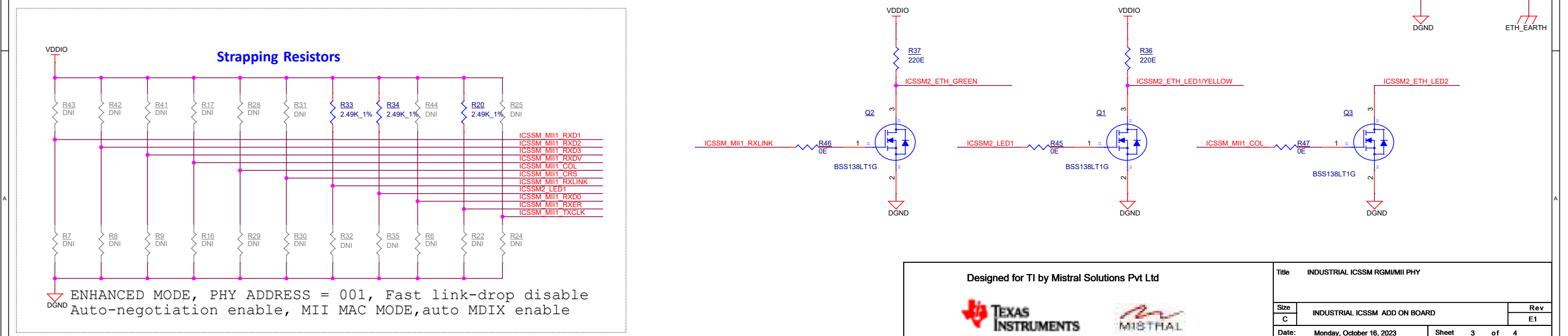
BLOCK DIAGRAM INDUSTRIAL ICSSM RGMII/MII ADD ON BOARD



PRU1 ICSSM RGMII/MII Ethernet



LED Driver MOSFETS

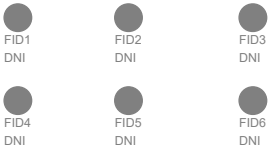


NOTES, HW & LABELS

ASSEMBLY NOTES

- 1. All MSL components should be baked as per JEDEC standard.
- 2. PCB should be baked at 120 degree for 8 hours.
- 3. Board assembly must comply with workmanship standards. IPC-A-610 Class 2, unless otherwise specified.
- 4. These assemblies are ESD sensitive, ESD precautions shall be observed.
- 5. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 6. Provide serial numbers to the assembled boards for identification.
- 7. The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

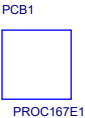
FIDUCIALS



LOGOs



BARE PCB



Designed for TI by Mistral Solutions Pvt Ltd



Title NOTES,HW &LABELS

Size C INDUSTRIAL ICSSM ADD ON BOARD

Rev

E1

Date: Monday, October 16, 2023 Sheet 4 of 4